In the Claims:

Please amend the claims as follows:

1.   (Previously Amended) A transducer ~~transitioning between electronic data transfer~~ ~~protocols of a jumper cable and an integrated circuit mounted on a substrate,~~ comprising:

a ~~base~~housing mountable on ~~the~~a substrate, the housing configured to receive a jumper cable, ~~and~~

an input/output (I/O) lead supported by the housing and configured to directly contact an I/O lead of ~~the~~an integrated circuit mounted on the substrate, and

electronic circuitry supported by the housing to transition between an electronic data transfer protocol of the jumper cable and an electronic data protocol of the integrated circuit.

2.   (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to electrically connect to the integrated circuit I/O lead independently of any electrically conductive path of the substrate.

3.   (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to contact the integrated circuit I/O lead at a transducer surface substantially parallel to a mounting surface of the substrate.

4.   (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to contact a pin I/O lead of the integrated circuit.

5.   (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to contact a solder ball lead of the integrated circuit.

6.   (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to contact the integrated circuit I/O lead at a transducer surface adjacent to a mounting surface of the substrate.

7.   (Original) The transducer of claim 1, further comprising a power input lead connectable to a power line of the substrate.

8.   (Original) The transducer of claim 1, further comprising a transductional device.

9.   (Original) The transducer of claim 1, wherein the transductional device is an opto-electronic device.

10.   (Original) The transducer of claim 1, wherein the transductional device is an electronic device.

11.   (Withdrawn) A method of connecting a transducer to an integrated circuit mounted on a substrate, comprising

        mounting the transducer to the substrate, and

        contacting an input/output (I/O) lead of the transducer to an I/O lead of the integrated circuit.

12.   (Withdrawn) The method of claim 11, wherein the transducer I/O lead electrically connects to the integrated circuit I/O lead independently of any electrically conductive path of the substrate.

13.   (Withdrawn) The method of claim 11, wherein the transducer I/O lead contacts the integrated circuit I/O lead at a transducer surface substantially parallel to a mounting surface of the substrate.

14.   (Withdrawn) The method of claim 11, wherein the transducer I/O lead contacts a pin I/O lead of the integrated circuit.

15.   (Withdrawn) The method of claim 11, wherein the transducer I/O lead contacts a solder ball lead of the integrated circuit.

16.   (Withdrawn) The method of claim 11, wherein the transducer I/O lead contacts the integrated circuit I/O lead at a transducer surface adjacent to a mounting surface of the substrate.

17.   (Withdrawn) The method of claim 11, wherein the transducer connects to a power line of the substrate when the transducer is mounted to the substrate.

18.   (Withdrawn) A system, comprising

a substrate,

an integrated circuit mounted on the substrate and having an input/output (I/O) lead, and

a transducer having an I/O lead configured to contact the I/O lead of the integrated circuit.

19.   (Withdrawn) The system of claim 18, wherein the transducer I/O lead is configured to electrically connect to the integrated circuit I/O lead independently of any electrically conductive path of the substrate.